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Model Single output						



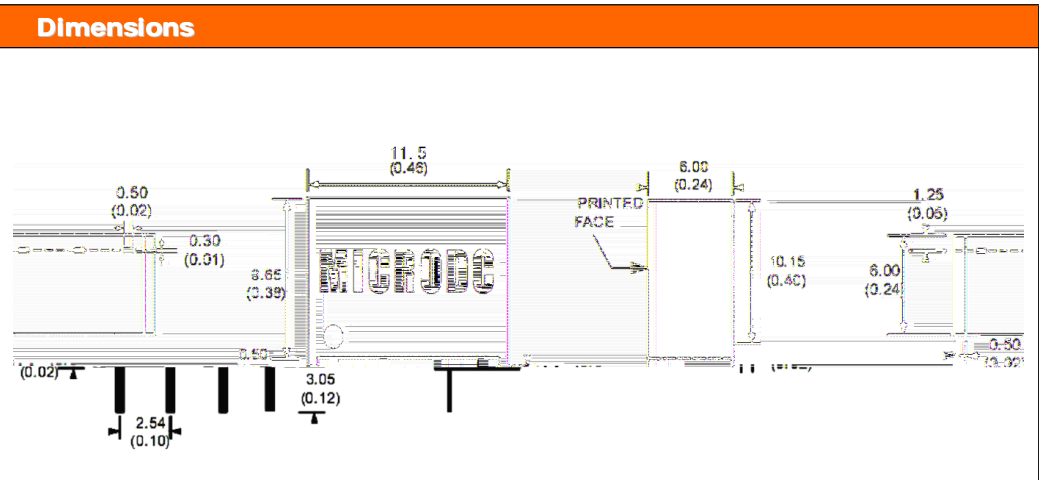
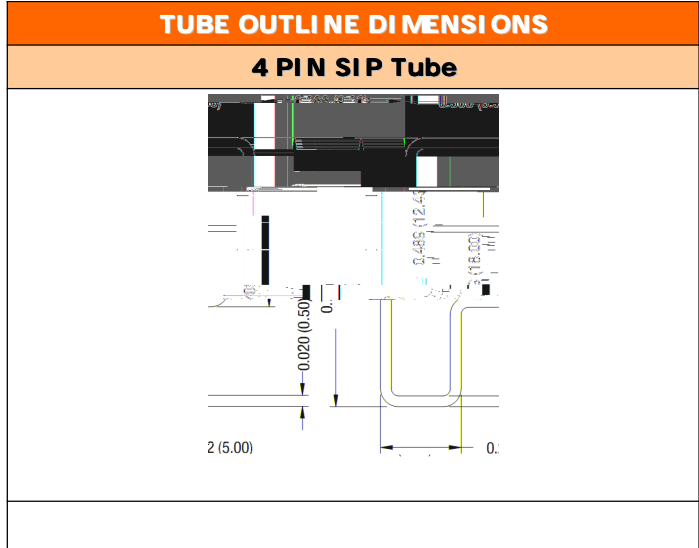
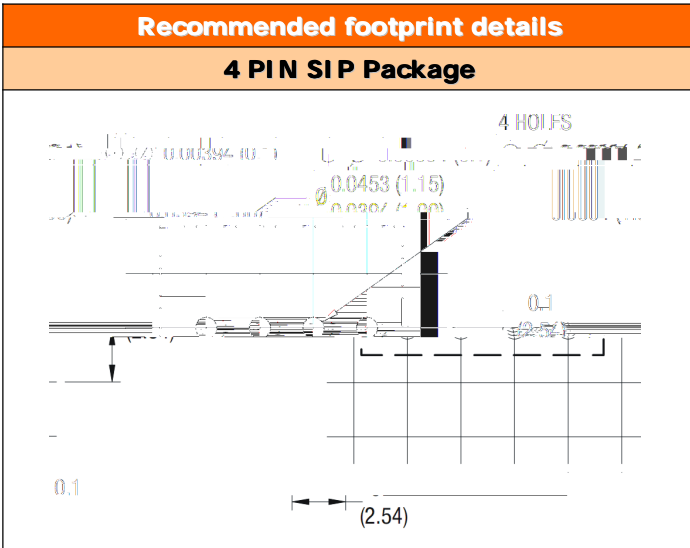
**CE REACH**  
MICRODC RESERVES THE COPYRIGHT

Input Specifications				
Parameters	Nominal	Typical	Maximum	Units
		-		

General Specifications				

Output Specifications				
Parameters	Conditions	Typical	Maximum	Units

Isolation Specifications				
Parameters	Condi ti ons	Typi cal	Rated	Uni ts



Pin Out Specifications	
Pin	Si ngl e

**RoHS COMPLIANT INFORMATION**

This series is compatible with RoHS soldering systems with a peak wave solder temperature of 300°C for 10 seconds. The pin termination finish on the SIP package type is Tin Plate, Hot Dipped over Matte Tin with Nickel Preplate. The DIP types are Matte Tin over Nickel Preplate. Both types in this series are backward compatible with Sn/Pb soldering systems.

**REACH COMPLIANT INFORMATION**

This series has proven that this product does not contain harmful chemicals, it also has harmful chemical substances through the registration, inspection and approval.

Microdc Professional Power module, Inc. makes no representation that the use of its products in the circuits described herein, or the use of other technical information contained herein, will not infringe upon existing or future patent rights. Specifications are subject to change without notice.

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